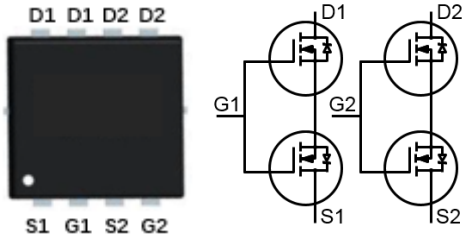
Dual N-Channel 250V Enhancement Mode MOSFETs

General Features

- Proprietary Advanced Planar Technology
- Rugged Polysilicon Gate Cell Structure
- Proprietary Advanced High Vth Technology
- RoHS Compliant
- Halogen-free available

BV_{DSS}	$R_{DS(ON)}$ (Max.)	I_D
250V	25 Ω	0.9A

PDFN3333



Ordering Information

Part Number	Package	Marking	Remark
FTF25N35DHVT	PDFN3333	25N35DHVT	Halogen Free

Absolute Maximum Ratings

T_A=25℃ unless otherwise specified

Symbol	Parameter	FTF25N35DHVT	Unit
V_{DSS}	Drain-to-Source Voltage[1]	250	V
I_D	Continuous Drain Current	0.9	A
I_{DM}	Pulsed Drain Current[2]	3.6	
P_D	Power Dissipation	16	W
V_{GS}	Gate-to-Source Voltage	±20	V
T_L	Soldering Temperature Distance of 1.6mm from case for 10 seconds	300	℃
T_J and T_{STG}	Operating and Storage Temperature Range	-55 to 150	

Caution: Stresses greater than those listed in the "Absolute Maximum Ratings" may cause permanent damage to the device.

Thermal Characteristics

Symbol	Parameter	FTF25N35DHVT	Unit
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	34	K/W

Electrical Characteristics

OFF Characteristics

T_A =25℃ unless otherwise specified

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions
BV_{DSS}	Drain-to-Source Breakdown Voltage	250	--	--	V	V_{GS}=0V, I_D=250μA
I_{DSS}	Drain-to-Source Leakage Current	--	--	1	μA	V_{DS}=250V，V_{GS}= 0V
		--	--	100	μA	V_{DS}=250V，V_{GS}= 0V T_J=125℃
I_{GSS}	Gate-to-Source Leakage Current	--	--	1	μA	V_{GS}=+20V, V_{DS}=0V
		--	--	-1		V_{GS}=-20V, V_{DS}=0V

ON Characteristics

T_A =25℃ unless otherwise specified

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions
$R_{DS(ON)}$	Static Drain-to-Source On-Resistance	--	12	25	Ω	V_{GS}=10V，I_D=100mA [3]
$V_{GS(TH)}$	Gate Threshold Voltage	2	--	5	V	V_{GD} =0V, I_D=250μA
$V_{GS(TH)\_REV}$	Reverse Gate Threshold Voltage	5	--	10	V	V_{GS} =0V, I_D=-5μA

NOTE：

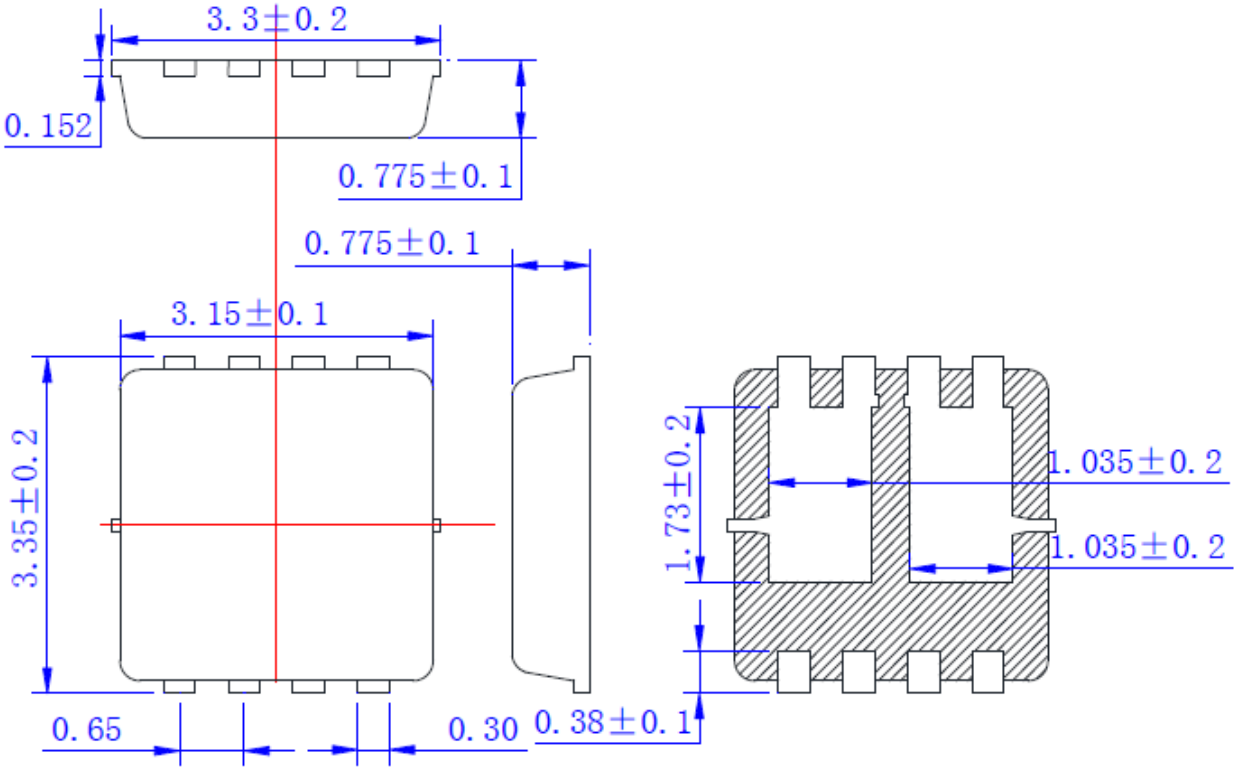
[1] T_J=+25℃ to +150℃

[2] Repetitive rating, pulse width limited by maximum junction temperature.

[3] Pulse width≤380μs; duty cycle≤2%.

Package Dimensions

PDFN3333



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